

PC451J00000F Series

Mini-flat Package, High Collector-emitter Voltage Photocoupler



■ Description

PC451J00000F Series contains an IRED optically coupled to a phototransistor.

It is packaged in a 4-pin Mini-flat. Input-output isolation voltage(rms) is 3.75kV. Collector-emitter voltage is 350V. CTR is MIN. 40% at input current of 5mA.

■ Features

- 1. 4-pin Mini-flat package
- 2. Double transfer mold package (Ideal for Flow Soldering)
- 3. High collector-emitter voltage (V_{CEO}: 350V)
- 4. High isolation voltage between input and output $(V_{iso(rms)}: 3.75kV)$
- 5. Lead-free and RoHS directive compliant

■ Agency approvals/Compliance

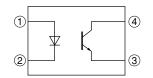
- Recognized by UL1577 (Double protection isolation), file No. E64380 (as model No. PC451)
- 2. Package resin: UL flammability grade (94V-0)

■ Applications

- 1. Telephones
- 2. Modems



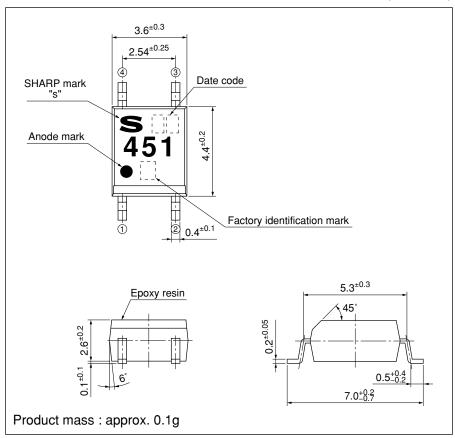
■ Internal Connection Diagram



- ① Anode
- ② Cathode
- 3 Emitter
- 4 Collector

■ Outline Dimensions

(Unit: mm)



Plating material: SnCu (Cu: TYP. 2%)



Date code (2 digit)

	1st o	digit		2nd digit		
	Year of p	roduction		Month of production		
A.D.	Mark	Mark A.D Mark		Month	Mark	
1990	A	2002	P	January	1	
1991	В	2003	R	February	2	
1992	С	2004	S	March	3	
1993	D	2005	T	April	4	
1994	Е	2006	U	May	5	
1995	F	2007	V	June	6	
1996	Н	2008	W	July	7	
1997	J	2009	X	August	8	
1998	K	2010	A	September	9	
1999	L	2011	В	October	0	
2000	M	2012	С	November	N	
2001	N	:	:	December	D	

repeats in a 20 year cycle

Factory identification mark

Factory identification Mark	Country of origin	
no mark	T	
	Japan	
	Indonesia	
	China	

^{*} This factory marking is for identification purpose only.

Please Contact the local SHARP sales reprsentative to see the actual status of the production.

Rank mark

There is no rank mark indicator.



■ Absolute Maximum Ratings

	Absolute Maximum Ratings $(T_a=25^{\circ}C)$							
	Parameter	Symbol	Rating	Unit				
	Forward current	I_{F}	50	mA				
Input	Reverse voltage	V_R	6	V				
1	Power dissipation	P	70	mW				
	Collector-emitter voltage	V _{CEO}	350	V				
Output	Emitter-collector voltage	V _{ECO}	6	V				
Out	Collector current	I_{C}	50	mA				
	Collector power dissipation	P _C	150	mW				
-	Total power dissipation	P _{tot}	170	mW				
	Operating temperature	Topr	-25 to +100	°C				
	Storage temperature	T _{stg}	-40 to +125	°C				
*1]	Isolation voltage	V _{iso (rms)}	3.75	kV				
*2 (Soldering temperature	T_{sol}	260	°C				

^{*1 40} to 60%RH, AC for 1 minute, f=60Hz *2 For 10s

■ Electro-optical Characteristics

 $(T_a=25^{\circ}C)$

	Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	Forward voltage		V_F	$I_F=20mA$	-	1.2	1.4	V
Input	Reverse Current		I_R	$V_R=4V$	_	_	10	μΑ
	Terminal capacitance		C_t	V=0, f=1kHz	_	30	250	pF
Output	Collector dark current		I_{CEO}	$V_{CE}=200V, I_{F}=0$	-	-	1000	nA
Output	Collector-emitter breakdown voltage		$\mathrm{BV}_{\mathrm{CEO}}$	$I_{C}=0.1 \text{mA}, I_{F}=0$	350	-	-	V
	Collector current		I_{C}	$I_F=5mA$, $V_{CE}=5V$	2	4	-	mA
	Collector-emitter saturation voltage		V _{CE (sat)}	$I_F=20mA$, $I_C=1mA$	-	0.1	0.3	V
Transfer	Isolation resistance		$R_{\rm ISO}$	DC500V, 40 to 60%RH	5×10 ¹⁰	1×10 ¹¹	-	Ω
charac- teristics	Floating capacitance		C_{f}	V=0, f=1MHz	_	0.6	1.0	pF
	Cut-off frequency		f_C	V_{CE} =5 V , I_{C} =2 mA , R_{L} =100 Ω , -3 dB	_	50	_	kHz
	Dagmanas tima	Rise time	t_r	V_{CE} =2V, I_{C} =2mA, R_{L} =100 Ω	_	4	10	μs
	Response time Fa	Fall time	t_{f}		_	5	12	μs



■ Model Line-up

Doolsooo	Taping				
Package	3 000 pcs/reel	750 pcs/reel			
Model No.	PC451J00000F	PC451TJ0000F			

Please contact a local SHARP sales representative to inquire about production status.

Sheet No.: D2-A00302EN



Fig.1 Forward Current vs. Ambient Temperature

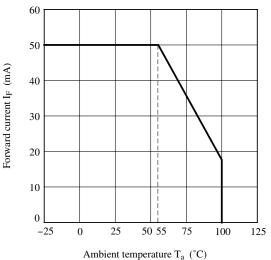


Fig.3 Collector Power Dissipation vs. Ambient Temperature

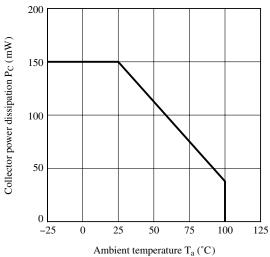


Fig.5 Peak Forward Current vs. Duty Ratio

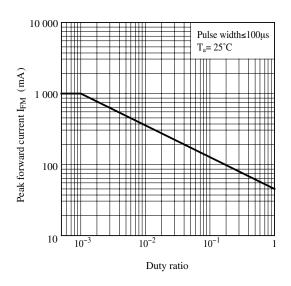


Fig.2 Diode Power Dissipation vs.
Ambient Temperature

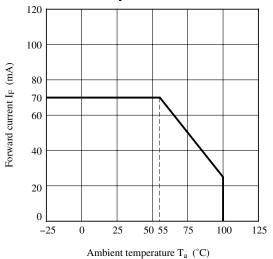


Fig.4 Total Power Dissipation vs. Ambient Temperature

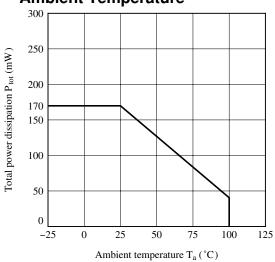


Fig.6 Forward Current vs. Forward Voltage

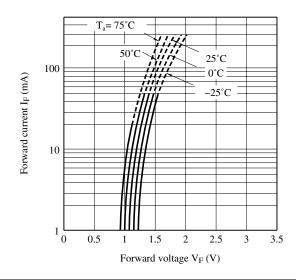




Fig.7 Current Transfer Ratio vs. Forward Current

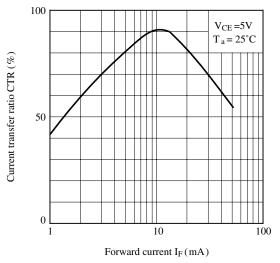


Fig.9 Relative Current Transfer Ratio vs.
Ambient Temperature

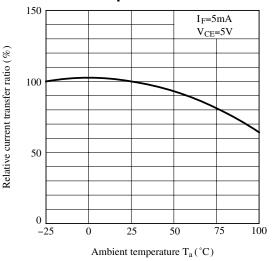


Fig.11 Collector Dark Current vs. Ambient Temperature

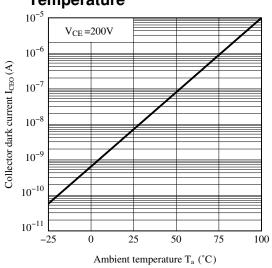


Fig.8 Collector Current vs. Collector-emitter Voltage

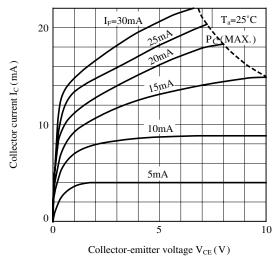


Fig.10 Collector - emitter Saturation Voltage vs. Ambient Temperature

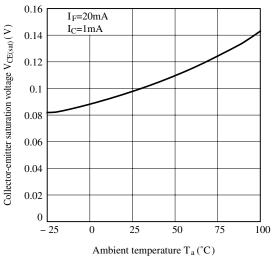


Fig.12 Response Time vs. Load Resistance

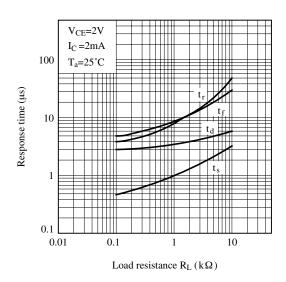
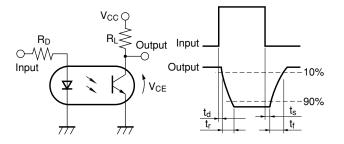




Fig.13 Test Circuit for Response Time



Please refer to the conditions in Fig.12

Fig.14 Frequency Response

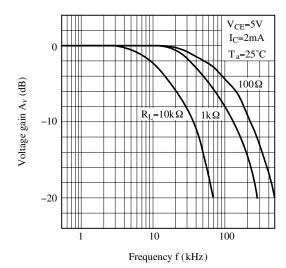
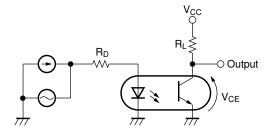
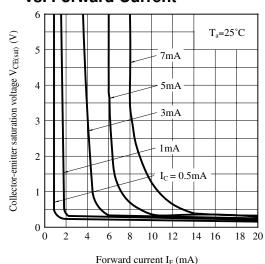


Fig.15 Test Circuit for Frequency Response



Please refer to the conditions in Fig.14

Fig.16 Collector-emitter Saturation Voltage vs. Forward Current



Remarks: Please be aware that all data in the graph are just for reference and not for guarantee.



■ Design Considerations

Design guide

While operating at I_F<1.0mA, CTR variation may increase.

Please make design considering this fact.

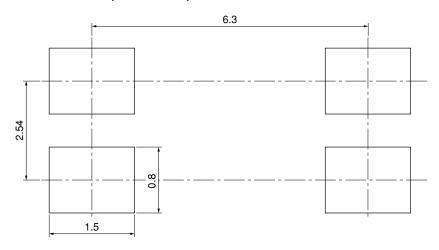
This product is not designed against irradiation and incorporates non-coherent IRED.

Degradation

In general, the emission of the IRED used in photocouplers will degrade over time.

In the case of long term operation, please take the general IRED degradation (50% degradation over 5 years) into the design consideration.

Recommended Foot Print (reference)



(Unit: mm)

[☆] For additional design assistance, please review our corresponding Optoelectronic Application Notes.



■ Manufacturing Guidelines

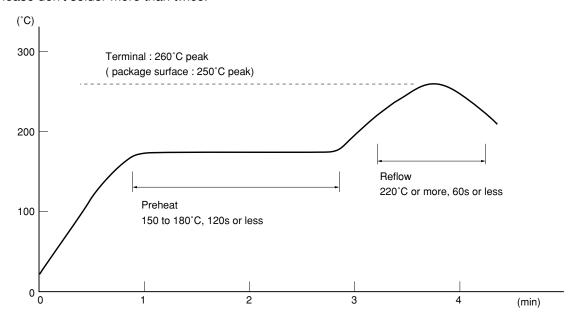
Soldering Method

Reflow Soldering:

Reflow soldering should follow the temperature profile shown below.

Soldering should not exceed the curve of temperature profile and time.

Please don't solder more than twice.



Flow Soldering:

Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 260°C and within 10s.

Preheating is within the bounds of 100 to 150°C and 30 to 80s.

Please don't solder more than twice.

Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400°C.

Please don't solder more than twice.

Other notices

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.



Cleaning instructions

Solvent cleaning:

Solvent temperature should be 45°C or below Immersion time should be 3 minutes or less

Ultrasonic cleaning:

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.

Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

Recommended solvent materials:

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol

In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this product.

Regulation substances: CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

•Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).



■ Package specification

● Tape and Reel package

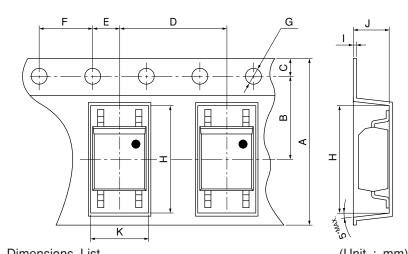
1. 3 000pcs/reel Package materials

Carrier tape: A-PET (with anti-static material)

Cover tape: PET (three layer system)

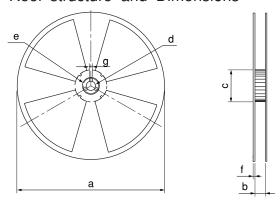
Reel: PS

Carrier tape structure and Dimensions



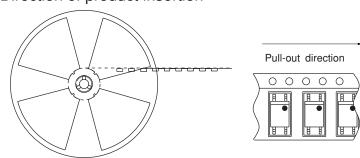
Dimension	IIS LIST				()	<i>,</i> ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,
A	В	C	D	Е	F	G
12.0 ^{±0.3}	5.5 ^{±0.1}	1.75 ^{±0.1}	8.0 ^{±0.1}	2.0±0.1	4.0 ^{±0.1}	φ1.5 + 8.1
Н	I	J	K			
$7.4^{\pm0.1}$	0.3 ^{±0.05}	3.1 ^{±0.1}	4.0 ^{±0.1}			

Reel structure and Dimensions



Dimensio	ns List	(Unit: mm)		
a	b	с	d	
370	13.5 ^{±1.5}	80 ^{±1.0}	13±0.5	
e	f	g		
21 ^{±1.0}	21 ^{±1.0} 2.0 ^{±0.5}			

Direction of product insertion



[Packing: 3 000pcs/reel]



2. 750 pcs / reel

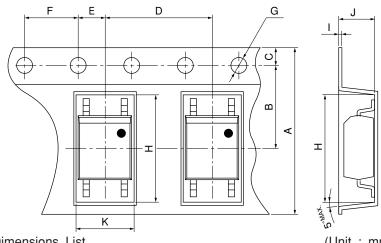
Package materials

Carrier tape: A-PET (with anti-static material)

Cover tape: PET (three layer system)

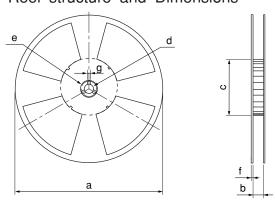
Reel: PS

Carrier tape structure and Dimensions



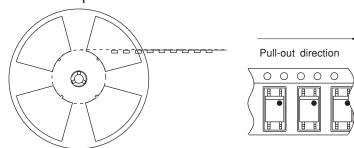
Dimensions List						(Unit: mm)		
A	В	С	D	Е	F	G		
12.0 ^{±0.3}	5.5 ^{±0.1}	1.75 ^{±0.1}	8.0 ^{±0.1}	2.0 ^{±0.1}	4.0 ^{±0.1}	φ1.5 + 0.1		
Н	I	J	K					
7 4±0.1	0 3±0.05	3 1±0.1	4 0±0.1					

Reel structure and Dimensions



	Dimensio	ns List	(Unit: mm)			
	a	b	с	d		
	180	180 13.5±1.5		13±0.5		
	e f 21 ^{±1.0} 2.0 ^{±0.5}		g			
			2.0±0.5			

Direction of product insertion



[Packing: 750pcs/reel]



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- --- Alarm equipment
- --- Various safety devices, etc.
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